

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hsin-Chieh Yao</td> <td>11/15/2012</td> </tr> <tr> <td>Chung-Ju Lee</td> <td>11/15/2012</td> </tr> <tr> <td>Hsiang-Huan Lee</td> <td>11/15/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hsin-Chieh Yao	11/15/2012	Chung-Ju Lee	11/15/2012	Hsiang-Huan Lee	11/15/2012
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Hsin-Chieh Yao	11/15/2012								
Chung-Ju Lee	11/15/2012								
Hsiang-Huan Lee	11/15/2012								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13724737</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13724737				
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CORRESPONDENCE DATA									
Fax Number:	2142000853								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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ATTORNEY DOCKET NUMBER:	24061.2253								
NAME OF SUBMITTER:	David M. O'Dell								
Total Attachments: 3 source=2253_Assignment#page1.tif source=2253_Assignment#page2.tif source=2253_Assignment#page3.tif									

OP \$40.00 13724737

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-------------------|----|--|
| (1) | Sunil Kumar Singh | of | 6 th Floor, No. 25, Lane 66, Sinjhuang Street
Hsinchu, Taiwan, R.O.C. |
| (2) | Hsin-Chieh Yao | of | 12F., No. 179, Guanxin N. Rd., East Dist.
Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Chung-Ju Lee | of | 6F, No. 65, Lane 19, Quan-Xin Road
Xin-Zhuang Settlement, Hsinchu City, Taiwan, R.O.C. |
| (4) | Hsiang-Huan Lee | of | No. 12, Alley 43, Lane 315, Syuefu E. Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C. |

have invented certain improvements in

INTERCONNECTION WIRES OF SEMICONDUCTOR DEVICES

for which we have filed and executed an application for Letters Patent of the United States of America on December 21, 2012, Serial No. 13/724,737; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Sunil Kumar Singh

Residence Address: 6th Floor, No. 25, Lane 66, Sinjhuang Street
Hsinchu, Taiwan, R.O.C.

Dated: _____

已離職

Inventor Signature

Inventor Name: Hsin-Chieh Yao

Residence Address: 12F., No. 179, Guanxin N. Rd., East Dist.
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2012/11/15

Hsin-Chieh Yao

Inventor Signature

Inventor Name: Chung-Ju Lee

Residence Address: 6F, No. 65, Lane 19, Quan-Xin Road
Xin-Zhuang Settlement, Hsinchu City, Taiwan, R.O.C.

Dated: 2012/11/15

Chung-Ju Lee

Inventor Signature

Docket No.: 2012-0692 / 24061.2253
Customer No.: 42717

Inventor Name: Hsiang-Huan Lee

Residence Address: No. 12, Alley 43, Lane 315, Syuefu E. Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

Dated: 2012. 11. 15.

Hsiang-Huan Lee
Inventor Signature
